	Material Comp © Copyright 2005. I international and Par	osition Dec PC, Bannockb n-American co	c laration ourn, Illinois. A opyright conver	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration	ation on a contract of the second sec	of the substances mpasses all lowe	within th er level ma	e manufactur aterials for w	rer listed i hich the n	tem. Note nanufactu	e: if the item is an arer has engineeri	n assembly with lower ng responsibility.	
1752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information					
Supplier	r Information															
Company name* Company				pany unique ID U			Unique ID Authority					Response Date*				
onsemi												2024-05	2024-05-07			
Contact N	ame		Title - Contact				Phone - Contact*				Email - Contact*					
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Authorize	d Representative*		Title - Representative				Phone - Representative*				Email - Representative*					
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date Version Manufacturing Site			uring Site		Weight*	UOM	Unit Type		
		1N5400					2024-05-07						1334.62	mg	Each	
Manufa	cturing Proccess Informa	tion		·								· · · · ·		· · · · ·		
	Terminal Plating / Grid Array Material			Cerminal Base Alloy J-STD-020 MSL			Peak Process Body Temperature Max Time at			Time at Peak	ak Temperature Number of Reflow Cycles					
		C	CU Alloy						С	30		secon	ids 3			
Comments	5															
for more	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed								
Directive 2015/863/EU amending RoHS Directive 2011/65/EU													
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of								
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted								
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).										
Exemption List Version	EL-2011/534/EU												
Declaration Signature													
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the								
Supplier Digital Signature	astislav Drska	Le											

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.67	mg	Supplier	Silicon (Si)	7440-21-3		6.67	mg
Die Attach Solder	46.69	mg	Supplier	Silver (Ag)	7440-22-4		1.1673	mg
			Α	Lead (Pb)	7439-92-1	7a	43.1882	mg
			Supplier	Tin (Sn)	7440-31-5		2.3345	mg
Lead Frame	731.48	mg	Supplier	Copper (Cu)	7440-50-8		731.48	mg
Mold Compound-Black	543.33	mg		Metal Hydroxide	proprietary data		27.1665	mg
			Supplier	Carbon Black (C)	1333-86-4		5.4333	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		407.4975	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		54.333	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		48.8997	mg
Plating	6.45	mg	Supplier	Tin (Sn)	7440-31-5		6.45	mg